1450.4 meeting minutes – 03/27/13

Attendees: Ernie Wahl, Jim O'Reilly, Mitsuo Fujii
Not present: Julia DiChiaro, Oleg Erlich, Markus Seuring, Ajay Khoche, Paul Reuter

Summary:

Line numbers are from syntax document dated March 26, 2013

- Line 751: ACCEPT: Section "6.4.1 Device to Tester Interface" with minor changes
- Line 1139: ACCEPT: For multi-project wafers, a Device block with multiple chips and no package may be defined.
- Line 3661: ACCEPT: Enum LevelGrp as proposed, remain open to additions, possibly subtractions.
- Line 3695 - 3714: ACCEPT: standard global variable names, leave open for review with regard to STDF compatibility.

Reference documents (If logged into your google account, can edit. If not, can only view.)

- Current Draft Syntax Document
- Issues List
- Namespace resolution examples document
- Communications spread sheet (scratchpad spreadsheet)
- Communications word doc (scratchpad word document)

Next meeting: 04/03/13

For reference STIL .4 information can be found at the IEEE STIL website: http://grouper.ieee.org/groups/1450/
(select the P1450.4 link from the table) or use the direct link http://grouper.ieee.org/groups/1450/dot4/index.html